

[METHOD OF FABRICATING FLIP CHIP BALL GRID ARRAY PACKAGE]

Abstract

A method of fabricating a flip chip ball grid array (FC-BGA) package is provided. First, a substrate including a first surface and a second surface is provided, wherein the first surface includes a plurality of cavities. Then, a plurality of flip chips is adhered in the cavities of the substrate. Thereafter, an underfill filling step is performed to fill an underfill between the substrate the flip chips. Then, a ball placement step is performed to attach a plurality of solder balls to a second surface of the substrate. Thereafter, the substrate is divided to separate a portion of the substrate adhering to the flip chips from a sidewall of the cavities.